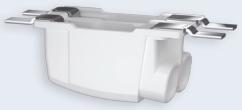
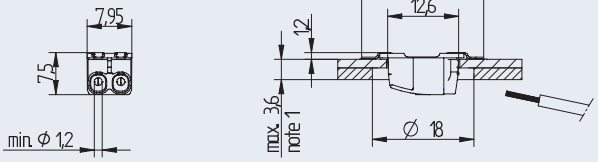
SMD Terminal block

46.112 · SMD Push through terminal block - Slim

technology for light





Note 1: Maximum thickness of PCB and luminaire heat sink shall not exceed 3.6 mm.

General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.

SMD-Push through terminal block with push wire contacts

2 pole - 46.112.1001.50

Direct insertion of solid and stranded, tinned wire ends

Wires can be released by twisting and pulling the wire simultaneously.

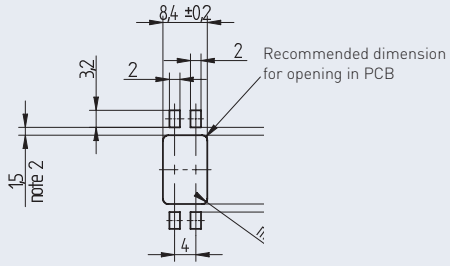
Mounting and wiring position: PCB bottom side

Ballast and PCB terminal block on one level

Machine-compatible "tape-and-reel" packaging

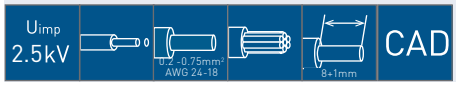
Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: Housing: PPA, white
Contact material: CuNiSiP
Contact surface: hot-dip tinned



Note 2: The minimum creepage distance has to be guaranteed, depends on the application.

Packaging data 46.112.1001.50	
Weight per piece	0.81 g
Pieces per coil	700 pieces
Coil diameter	15"
Weight per coil	0.976 kg
Number of coils per cardboard	10 pieces
Number of SMD terminal blocks per cardboard	7.000 pieces
Weigth per cardboard	9.76 kg
Weight cardboard	1.26 kg
Dimensions cardboard (LxBxH)	400 x 355 x 365 mm
Total weight	11.02 kg



Connection data	
Connection technology	Push wire contacts
Solid wires	0.2 - 0.75 mm², AWG 24-18
Stranded, tinned wires	0.2 - 0.5 mm², AWG 24-20
Strip length	8 +1 mm
Conductor entry angle to the PCB	0 - 10°
Wire release function by	Twisting and Pulling
Pull-out force according to DN 60999-1	
0.2 mm²	min. 10 N
0.34 mm²	min. 15 N
0.5 mm²	min. 20 N
0.75 mm²	min. 30 N
Insertion force	max. 10 N

Geometrical data	
Pin spacing	4 mm / 0.157 inch
Width	7.95 mm / 0.31 inch
Height	7.5 mm / 0.295 inch
Depth	21.7 mm / 0.85 inch
Reel diameter of tape-and-reel packaging	330 mm (13")
Reel width	32 mm
Pitch distance	16 mm
Packaging unit tape-and-Reel	500
Packaging unit cardboard	5.000 (10 reels)

Material data	
Insulating material group	I
Insulating material	PPA, white
PTI	600
Flammability class, based on UL UL 94	V0
Contact material	CuNiSiP
Contact surface	hot-dipped tinned

Mechanical data	
Mounting position	PCB bottom side
Mounting type	Lead-free reflow soldering

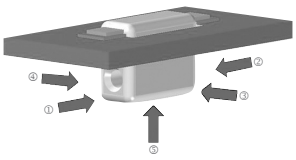
Temperature data	
Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 125 °C
T-classification according to IEC 60998-1 para. 12	120°

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1) für Leiterplattentyp FR4 1.0 mm	
Rated voltage (III / 3)	200 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	250 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	400 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1) für Leiterplattentyp IMS	
Rated voltage (III / 3)	63 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	160 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	320 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to UL 1977	
Rated voltage UL 1977	300 V
Rated current UL 1977	9 A

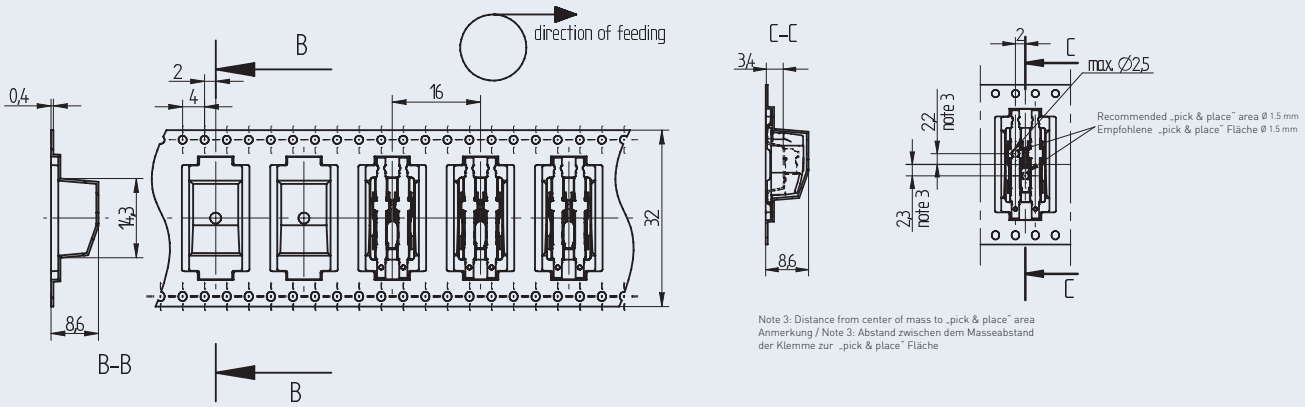
Country specific certificates	
VDE ENEC	EN 60947
UL	cURus, File No. E-365006

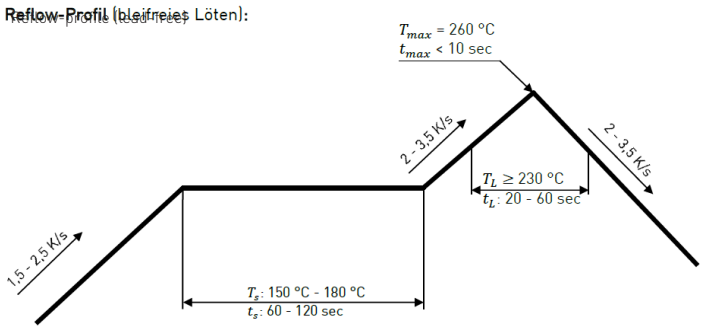
Shear forces according to IEC 62137-1-2: 2007. These values are maximum values that apply only for impuls, not for continuous load.	
Direction 1 shear force along	160
Direction 2 shear force along	100
Direction 3 shear force across	30
Direction 4 shear force across	30
Direction 5 pull-off force	30

Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C.
Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150)